

ABSTRACT

The present invention provides an interconnect useful for the prevention of ESD/EOS damage to electrical components. The present invention provides for interconnects that include at least two conductive wires or leads engaged on at least one surface by a carbonizable and ablative material. The conductive wires may each include a branched dead end lead portion interleaved with the branched dead end lead portion of the other. Alternatively, the conductive wires may extend in close proximity to each other in a curved or sinuous or serpentine or backtracking pattern. An interconnect in accord with the present invention may include a substrate substantially supporting the conductive wires except at predetermined locations or proposed shunt sites wherein there is at least one through hole in the substrate.